

## PATENT ASSIGNMENT COVER SHEET

Electronic Version v1.1  
 Stylesheet Version v1.2

EPAS ID: PAT5827866

<b>SUBMISSION TYPE:</b>	NEW ASSIGNMENT
<b>NATURE OF CONVEYANCE:</b>	ASSIGNMENT
<b>CONVEYING PARTY DATA</b>	
<b>Name</b>	<b>Execution Date</b>
YUN LEE	08/08/2017
CHEN-MING LEE	08/08/2017
FU-KAI YANG	08/08/2017
YI-JYUN HUANG	08/08/2017
SHENG-HSIUNG WANG	08/08/2017
MEI-YUN WANG	08/08/2017
<b>RECEIVING PARTY DATA</b>	
<b>Name:</b>	TAIWAN SEMICONDUCTOR MANUFACTURING CO., LTD.
<b>Street Address:</b>	8, LI-HSIN RD. 6
<b>Internal Address:</b>	HSINCHU SCIENCE PARK
<b>City:</b>	HSINCHU
<b>State/Country:</b>	TAIWAN
<b>Postal Code:</b>	300-78
<b>PROPERTY NUMBERS Total: 1</b>	
<b>Property Type</b>	<b>Number</b>
<b>Application Number:</b>	16688071
<b>CORRESPONDENCE DATA</b>	
<b>Fax Number:</b>	(214)200-0853
<i>Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.</i>	
<b>Phone:</b>	2146515000
<b>Email:</b>	ipdocketing@haynesboone.com
<b>Correspondent Name:</b>	HAYNES AND BOONE, LLP IP SECTION
<b>Address Line 1:</b>	2323 VICTORY AVENUE
<b>Address Line 2:</b>	SUITE 700
<b>Address Line 4:</b>	DALLAS, TEXAS 75219
<b>ATTORNEY DOCKET NUMBER:</b>	2017-0470/24061.3575US03
<b>NAME OF SUBMITTER:</b>	YILUN WANG
<b>SIGNATURE:</b>	/Yilun Wang/
<b>DATE SIGNED:</b>	11/19/2019

PATENT

**Total Attachments: 3**

source=24061.3575US03 - Assignment#page1.tif

source=24061.3575US03 - Assignment#page2.tif

source=24061.3575US03 - Assignment#page3.tif

**ASSIGNMENT**

WHEREAS, we,

- |     |                   |    |  |
|-----|-------------------|----|--|
| (1) | Yun Lee           | of | Taipei County, Taiwan, Republic of China   |
| (2) | Chen-Ming Lee     | of | Taoyuan County, Taiwan, Republic of China  |
| (3) | Fu-Kai Yang       | of | Hsinchu City, Taiwan, Republic of China    |
| (4) | Yi-Jyun Huang     | of | New Taipei City, Taiwan, Republic of China |
| (5) | Sheng-Hsiung Wang | of | Hsinchu County, Taiwan, Republic of China  |
| (6) | Mei-Yun Wang      | of | Hsin-Chu, Taiwan, Republic of China        |

have invented certain improvements in

**METHODS FOR REDUCING CONTACT DEPTH VARIATION  
IN SEMICONDUCTOR FABRICATION**

for which we have executed an application for Letters Patent of the United States of America,

\_\_\_\_\_ of even date filed herewith; and  
X filed on 08-30-2017 and assigned application number 15/690,709; and

WHEREAS, we authorize the attorney of record to update this document to include Patent Office information as deemed necessary (i.e., filing date, serial number, etc.);

WHEREAS, Taiwan Semiconductor Manufacturing Co., Ltd., ("TSMC"), 8, Li-Hsin Rd. 6, Hsinchu Science Park, Hsinchu, Taiwan 300-78, Republic of China is desirous of obtaining the entire right, title, and interest in, to and under the said invention and the said application in the United States of America and in any and all countries foreign thereto;

NOW, THEREFORE, for good and valuable consideration, the receipt and sufficiency of which is hereby acknowledged, and other good and valuable consideration, we have sold, assigned, transferred and set over, and by these presents do hereby sell, assign, transfer and set over, unto the said TSMC, its successors, legal representatives, and assigns, the entire right, title, and interest in, to and under the said invention, and the said application, and all divisional, renewal, substitutional, and continuing applications thereof, and all Letters Patent of the United States of America which may be granted thereon and all reissues and extensions thereof, and all applications for Letters Patent which may be filed for said invention in any country or countries foreign to the United States of America, and all extensions, renewals, and reissues thereof, and all prior patents and patent applications from which a filing priority of the above-described patent application may be obtained, including the right to collect past damages; and we hereby authorize and request the Commissioner of Patents of the United States of America, and any official of any country or countries foreign to the United States of America, whose duty it is to issue patents on applications as aforesaid, to issue all Letters Patent for said invention to the said TSMC, its successors, legal representatives and assigns, in accordance with the terms of this instrument.

Docket No.: P20170470US00/24061.3575US01

Customer No.: 42717

AND WE HEREBY covenant that we have full right to convey the entire interest herein assigned, and that we have not executed, and will not execute, any agreement in conflict herewith.

AND WE HEREBY further covenant and agree that we will communicate to said TSMC, its successors, legal representatives and assigns, any facts known to us respecting said invention, and testify in any legal proceedings, sign all lawful papers, execute all divisional, renewal, substitutional, continuing, and reissue applications, make all rightful declarations and/or oaths and generally do everything possible to aid the said TSMC, its successors, legal representatives and assigns, to obtain and enforce proper patent protection for said invention in all countries.

---

Inventor Name: Yun Lee

Residence Address: 3F, #46, Jhong 3<sup>rd</sup> Rd., XiZhi City  
Taipei County, Taiwan, Republic of China

Dated: 8/8/2017Yun Lee  
Inventor Signature

---

Inventor Name: Chen-Ming Lee

Residence Address: Rm. 4, 12F, No. 2, Ln. 10, Qingshan 5<sup>th</sup> St., Yangmei City  
Taoyuan County 326, Taiwan, Republic of China

Dated: 8/8/2017Chen-Ming Lee  
Inventor Signature

---

Inventor Name: Fu-Kai Yang

Residence Address: 7F.-2, No. 47, Lane 459, Sec. 1, Guang-Fu Rd.  
Hsinchu City 300, Taiwan, Republic of China

Dated: 8/8/2017Yang Fu Kai  
Inventor Signature

---

Inventor Name: Yi-Jyun Huang

Residence Address: 3F, No. 32, Ln. 284, Yongping Rd., Yonghe Dist.  
New Taipei City 234, Taiwan, Republic of China

Dated: 8/8/2017Yi-Jyun Huang  
Inventor Signature

Docket No.: P20170470US00/24061.3575US01  
Customer No.: 42717

---

Inventor Name: Sheng-Hsiung Wang

Residence Address: 4F, No. 72, Fuxing 7<sup>th</sup> Rd., Zhubei City  
Hsinchu County 302, Taiwan, Republic of China

Dated: 2017/8/8

Sheng-Hsiung Wang  
Inventor Signature

---

Inventor Name: Mei-Yun Wang

Residence Address: No. 49, Tze-Chiang Six Street, Chu-Pei City  
Hsin-Chu, Taiwan, Republic of China

Dated: 8/8/2017

Mei-Yun Wang  
Inventor Signature